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SEMICONDUCTOR MANUFACTURING INTERNATIONAL CORPORATION

中 芯 國 際 集 成 電 路 製 造 有 限 公 司 *

(Incorporated in the Cayman Islands with limited liability)

(Stock code: 0981)

COMPLETION OF THE ISSUE OF US\$500 MILLION 4.125% BONDS DUE 2019

Joint Lead Managers



J.P.Morgan

The Company is pleased to announce that completion of the issue of the Bonds in the principal amount of US\$500,000,000 took place on 7 October 2014.
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Reference is made to the announcement of the Company dated 25 September 2014 relating to, among other things, the proposed issue of the Bonds (the “**Announcement**”). Unless the context otherwise requires, capitalised terms in this announcement shall have the same meanings as those defined in the Announcement.

* For identification purposes only

The Company is pleased to announce that completion of the issue of the Bonds in the principal amount of US\$500,000,000 took place on 7 October 2014. The Company has received approval in-principle from the SGX-ST for the listing and quotation of the Bonds. The Bonds are expected to be listed on the SGX-ST on 8 October 2014. The approval in-principle granted for the listing and quotation of the Bonds is not to be taken as an indication of the merits of the Company or any other subsidiary or associated company of the Company or the Bonds. The estimated net proceeds (net of fees, commissions and expenses) from the issue of the Bonds will be approximately US\$491 million.

By order of the Board
Semiconductor Manufacturing International Corporation
Dr. Tzu-Yin Chiu
Chief Executive Officer and Executive Director

Shanghai, 7 October 2014

As at the date of this announcement, the Directors are:

Executive Directors

Zhang Wenyi (*Chairman*)
Tzu-Yin Chiu (*Chief Executive Officer*)
Gao Yonggang (*Chief Financial Officer*)

Non-executive Directors

Chen Shanzhi (*Li Yonghua as his Alternate*)
Lawrence Juen-Yee Lau (*Datong Chen as his Alternate*)
Zhou Jie

Independent Non-executive Directors

William Tudor Brown
Sean Maloney
Frank Meng
Lip-Bu Tan
Carmen I-Hua Chang